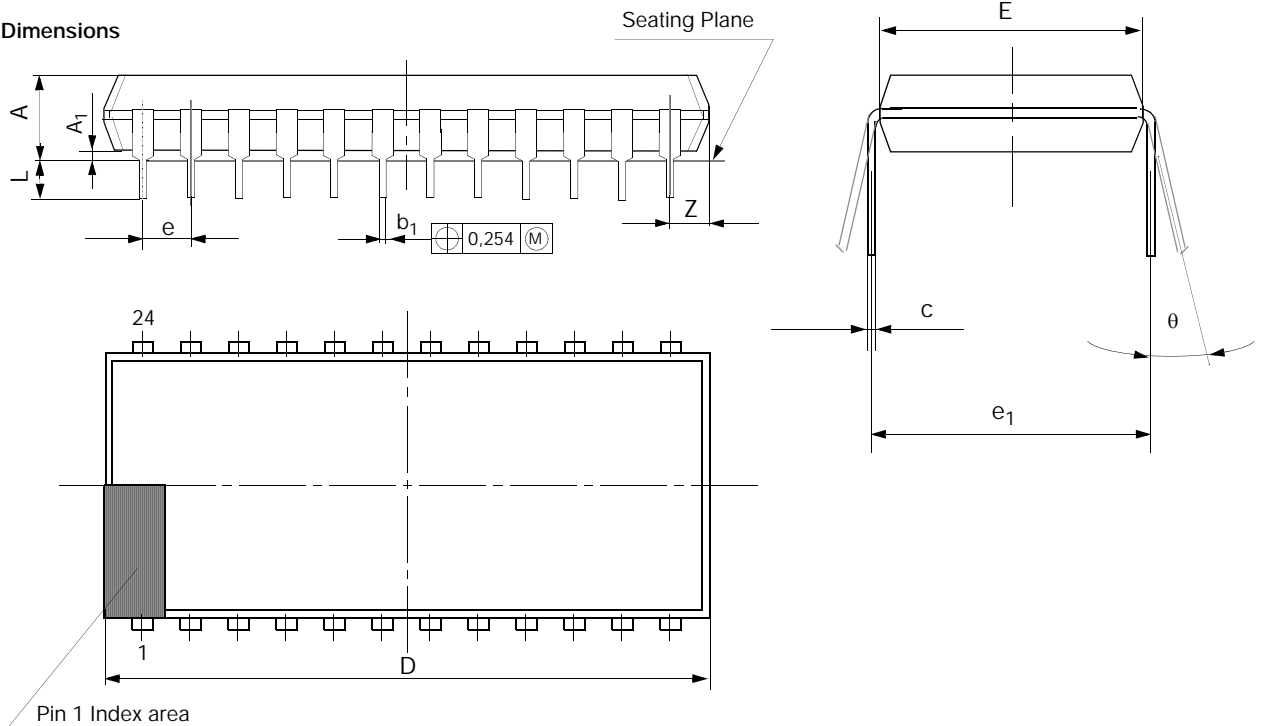
	Package PDIP24 (600 mil)	MDS 712
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Supersedes
Edition 11.95

Dimensions in millimetres

Based on IEC 191-2N: Type 051G03

1 Dimensions



Dimensions of Sub-Group B1	
A_{\max}	5,10
$A_{1\min}$	0,38
$b_{1\min}^{**}$	0,35
$b_{1\max}^{**}$	0,59
c_{\min}	0,20
c_{\max}	0,36
e_{nom}	2,54
$e_{1\text{nom}}$	15,24
E_{\min}^*	13,60
E_{\max}^*	14,30
L_{\min}	2,60
Z_{\max}	2,54

Dimensions of Sub-Group C1	
A_{\min}	3,00
$A_{1\max}$	1,80
L_{\max}	5,00
D_{\min}^*	31,50
D_{\max}^*	32,40
θ_{\min}	0°
θ_{\max}	15°

* without mold-flash

** The lead position tolerance requires slots with a minimum diameter of 0,7mm. The spacing between adjacent slots is 2,54mm.

- 2 Weight** $\leq 3,5$ g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating

Zentrum Mikroelektronik Dresden AG		
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